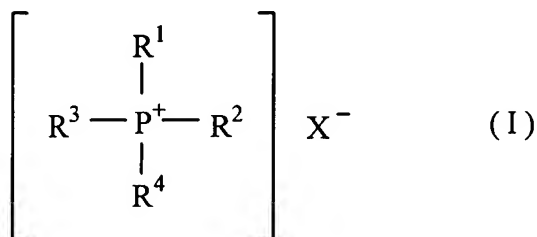
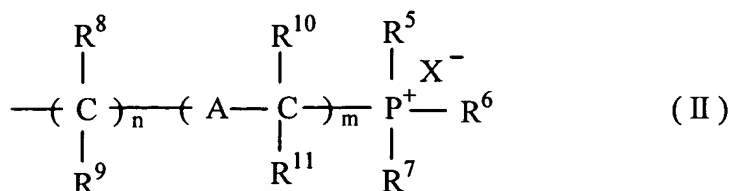


AMENDMENTS TO THE CLAIMS

1. (Currently amended) An epoxy resin composition comprising an epoxy resin, ~~a~~an acid anhydride hardening agent and a hardening accelerator as indispensable ingredients, wherein said hardening accelerator is a phosphonium compound represented by the following formula (I):



wherein X represents a halogen atom, SbF₆, AsF₆, PF₆, BF₄ or BPh₄, and R¹ to R⁴ are the same or different, and are an optionally substituted alkyl group, an optionally substituted aryl group, an optionally substituted aralkyl group, an optionally substituted diarylmethyl group or a group represented by the following formula (II):



wherein R⁵ to R⁷ are the same or different, and are an optionally substituted alkyl group, an optionally substituted aryl group, an optionally substituted aralkyl group or an optionally substituted diarylmethyl group,

R⁸ to R¹¹ are the same or different, and are a hydrogen atom, an optionally substituted alkyl group or an optionally substituted aryl group,

A is an optionally substituted aromatic hydrocarbon ring,

n is an integer of 1 to 5, m is 0 or 1, and

~~X represents a halogen atom, and SbF₆, AsF₆, PF₆, BF₄ or BPh₄~~

X is as defined in the formula (I);

provided that at least one of R¹ to R⁴ is a group represented by the formula (II),
~~and when m is 1, or any one of R¹ to R⁴ and any one of R⁵ to R⁷ R⁵-R⁷ may be~~
 combined together to form a lower alkylene group which forms a heterocyclic ring
 containing two phosphorus atoms, ~~and X is as defined in the formula (II).~~

2. (Currently amended) The epoxy resin composition according to claim 1 wherein the phosphonium compound is one or more ~~kinds of~~ phosphonium compound selected from the group consisting of

(a) a phosphonium compound wherein, in the above formula (I), at least one of R^1 to R^4 is a group represented by the formula (II), R^5 to R^7 are the same or different, and are a phenyl group, an optionally substituted benzyl group, a naphthylmethyl group, an optionally substituted diphenylmethyl group or an optionally substituted alkyl group, R^8 is a hydrogen atom, R^9 is a hydrogen atom or a phenyl group, n is an integer of 1 to 4, m is 0, and the rest of R^1 to R^4 is a phenyl group, an optionally substituted benzyl group, a naphthylmethyl group, an optionally substituted diphenylmethyl group or an optionally substituted alkyl group,

(b) a phosphonium compound wherein, in the above formula (I), R^2 is a group represented by the formula (II), R^6 , R^7 and R^9 are a phenyl group, R^8 is a hydrogen atom, m is 0, n is 2, R^1 and R^5 are combined together to form a C_{1-4} alkylene group, and R^3 and R^4 are a phenyl group, and

~~(c) a phosphonium compound wherein, in the above formula (I), R^1 is a group represented by the formula (II), R^5 to R^7 are a phenyl group or a group represented by the formula: $-(CH_2)_p-PPh_2$ (wherein, p is an integer of 1 to 4), R^8 to R^{11} are a hydrogen atom, A is an optionally substituted benzene ring, m and n are 1, and R^2 to R^4 are a phenyl group or a group represented by the formula: $-(CH_2)_p-PPh_2$ (wherein, p is an integer of 1 to 4),~~

~~(d)~~(c) a phosphonium compound wherein, in the above formula (I), R^2 is a group represented by the formula (II), R^6 and R^7 are a phenyl group, R^8 to R^{11} are a hydrogen atom, A is an optionally substituted benzene ring, m and n are 1, R^1 and R^5 are combined together to form a C_{1-8} alkylene group, and R^3 and R^4 are a phenyl group.

3. (Currently amended) The epoxy resin composition according to claim 1, wherein the amount of a the phosphonium compound ~~to be added~~ is 0.05 to 5 parts by weight (phr) relative to 100 parts by weight (phr) of epoxy resin.

4. (Original) The epoxy resin composition according to claim 1, wherein the epoxy resin comprises a triazine derivative epoxy resin.

5. (Original) A hardened resin which is obtained by heating and curing the epoxy resin composition according to claim 1.